L Number	Hits	Search Text	DB	Time stamp
1	26	("6594542" "6531399" "6494765" "6439964" "2		"80044097046047945"!"
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_			IBM_TDB	0004/00/04 05 55
2	2043	,	USPAT;	2004/08/04 07:55
		senses (strain adj gauge))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_			IBM_TDB	
3	4	(1 2004408904 "68409 /5"
		and (friction near3 (sensor sensors	US-PGPUB;	
		sensing senses (strain adj gauge)))	EPO; JPO;	
			DERWENT;	
4	2705284	 wafer wafers substrate substrates	IBM_TDB USPAT;	2004/08/04 08:01
4	2/03284	semiconductor semiconductors	US-PGPUB;	2004/08/04 08.01
		Semiconductor semiconductors	EPO; JPO;	
	İ		DERWENT;	
			IBM TDB	
6	176	(friction near3 (sensor sensors sensing	USPAT;	2004/08/04 08:02
0	1/6	senses (strain adj gauge))) same (wafer	US-PGPUB;	2004/08/04 08.02
		wafers substrate substrates semiconductor	EPO; JPO;	
		semiconductors)	DERWENT;	
		Semiconductors	IBM TDB	
8	363	(friction near3 (sensor sensors sensing	USPAT;	2004/08/04 08:02
0	363	senses (strain adj gauge))) and (wafer	US-PGPUB;	2004/08/04 08:02
		wafers substrate substrates semiconductor	EPO; JPO;	
		semiconductors)	DERWENT;	
		Semiconductors /	IBM TDB	
7	139	(friction near3 (sensor sensors sensing	USPAT;	2004/08/04 08:03
,	139	senses (strain adj gauge))) with (wafer	US-PGPUB;	2004/00/04 00:05
		wafers substrate substrates semiconductor	EPO; JPO;	
		semiconductors)	DERWENT;	
		Semiconductors /	IBM TDB	
9	15464	(distance gap) adj (sensor sensors sensing	USPAT;	2004/08/04 08:19
,	15404	sensed)	US-PGPUB;	2004/00/04 00:13
		Sensea,	EPO; JPO;	
			DERWENT;	
			IBM TDB	-
10	2	((friction near3 (sensor sensors sensing	USPAT;	2004/08/04 08:10
10	_	senses (strain adj gauge))) with (wafer	US-PGPUB;	
		wafers substrate substrates semiconductor	EPO; JPO;	
		semiconductors)) and ((distance gap) adj	DERWENT;	
		(sensor sensors sensing sensed))	IBM TDB	
11	2336107	gap distance	USPAT;	2004/08/04 08:10
		3.1	US-PGPUB;	
			EPO; JPO;	
			DERWENT;]
			IBM TDB	
12	3	((("6594542" "6531399" "6494765" "6439964"	'20 50P2AO O 52166	"2063798794 08342975"
		and (friction near3 (sensor sensors	US-PGPUB;	
		sensing senses (strain adj gauge)))) and	EPO; JPO;	
		(gap distance)	DERWENT;	İ
			IBM_TDB	
13	719	(wafer wafers substrate substrates	USPĀT;	2004/08/04 08:12
		semiconductor semiconductors) same	US-PGPUB;	
		((distance gap) adj (sensor sensors	EPO; JPO;	
		sensing sensed))	DERWENT;	
			IBM_TDB	
14	363909	abrasive abrade abrading abrades abrasives	USPĀT;	2004/08/04 08:13
		polish polishes polished polishing	US-PGPUB;	
		polisher polishers	EPO; JPO;	
			DERWENT;	
			TOM MOD	·
		į	IBM_TDB	
15	19	((wafer wafers substrate substrates	USPAT;	2004/08/04 08:13
15	19	semiconductor semiconductors) same	USPĀT; US-PGPUB;	2004/08/04 08:13
15	19	semiconductor semiconductors) same ((distance gap) adj (sensor sensors	USPĀT; US-PGPUB; EPO; JPO;	2004/08/04 08:13
15	19	semiconductor semiconductors) same ((distance gap) adj (sensor sensors sensing sensed))) same (abrasive abrade	USPĀT; US-PGPUB; EPO; JPO; DERWENT;	2004/08/04 08:13
15	19	semiconductor semiconductors) same ((distance gap) adj (sensor sensors	USPĀT; US-PGPUB; EPO; JPO;	2004/08/04 08:13

				·	
16	2	(((wafer wafers substrate substrates	USPAT;	2004/08/04	08:15
		semiconductor semiconductors) same	US-PGPUB; EPO; JPO;		
		((distance gap) adj (sensor sensors sensing sensed))) same (abrasive abrade	DERWENT;		
		abrading abrades abrasives polish polishes	IBM TDB		
		polished polishing polisher polishers))	12.1_122		
		and (friction near3 (sensor sensors			
		sensing senses (strain adj gauge)))			
21	106394	(distance gap) with (sensor sensors	USPAT;	2004/08/04 (08:19
•		sensing sensed)	US-PGPUB;		
1			EPO; JPO;		
ĺ	İ		DERWENT;		
24	19	//friction many /company concern concing	IBM_TDB USPAT;	2004/08/04	00.33
24	19	((friction near3 (sensor sensors sensing senses (strain adj gauge))) with (wafer	US-PGPUB;	2004/00/04	00.33
		wafers substrate substrates semiconductor	EPO; JPO;		
		semiconductors)) and ((distance gap) with	DERWENT;		
		(sensor sensors sensing sensed))	IBM TDB		
25	4509	(wafer wafers substrate substrates	USPĀT;	2004/08/04 (08:25
		semiconductor semiconductors) with	US-PGPUB;		
		((distance gap) with (sensor sensors	EPO; JPO;		
		sensing sensed))	DERWENT;		
26	92	//wafan wafana subahnaha subahnaha	IBM_TDB USPAT;	2004/08/04	08.25
26	92	((wafer wafers substrate substrates semiconductor semiconductors) with	US-PGPUB;	2004/08/04 (06:23
	į.	((distance gap) with (sensor sensors	EPO; JPO;		
ļ		sensing sensed))) and (strain adj gauge)	DERWENT;		
		, , , , , , , , , , , , , , , , , , , ,	IBM TDB		
27	13	((wafer wafers substrate substrates	USPĀT;	2004/08/04 (08:25
		semiconductor semiconductors) with	US-PGPUB;		
1		((distance gap) with (sensor sensors	EPO; JPO;		
•		sensing sensed))) and (friction near3	DERWENT;	İ	
		(sensor sensors sensing senses (strain adj	IBM_TDB		
28	66948	gauge))) dummy	USPAT;	2004/08/04	กละสก
20	00340	duniny	US-PGPUB;	2004/00/04 (00.50
			EPO; JPO;		
			DERWENT;		
			IBM_TDB		
29	12163	dummy with (wafer wafers substrate	USPAT;	2004/08/04 (08:32
		substrates semiconductor semiconductors)	US-PGPUB;		
			EPO; JPO;		
			DERWENT; IBM TDB		
30	7	 (dummy with (wafer wafers substrate	USPAT;	2004/08/04 (08:31
30	,	substrates semiconductor semiconductors))	US-PGPUB;	2001, 00, 01	
	1	and (friction near3 (sensor sensors	EPO; JPO;		
		sensing senses (strain adj gauge)))	DERWENT;		
			IBM_TDB		
31	15002		USPAT;	2004/08/04 (08:32
	1	substrates semiconductor semiconductors)	US-PGPUB;		
	1	·	EPO; JPO; DERWENT;		
	1		IBM TDB		
32	3	((friction near3 (sensor sensors sensing	USPAT;	2004/08/04 (08:33
\ \frac{1}{2}		senses (strain adj gauge))) with (wafer	US-PGPUB;		
		wafers substrate substrates semiconductor	EPO; JPO;		
		semiconductors)) and (dummy same (wafer	DERWENT;		
	1	wafers substrate substrates semiconductor	IBM_TDB		
	0055005	semiconductors))	.,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	0004/00/01	00 - 22
33	3255821	condition conditioner conditioning	USPAT;	2004/08/04 (u v: 33
		conditions conditioners	US-PGPUB; EPO; JPO;		
			DERWENT;		
			IBM TDB		
34	3555	(dummy with (wafer wafers substrate	USPAT;	2004/08/04 (08:34
		substrates semiconductor semiconductors))	US-PGPUB;		
		and (condition conditioner conditioning	EPO; JPO;		
		conditions conditioners)	DERWENT;		
	1		IBM_TDB	<u> </u>	

35	497	(dummy with (wafer wafers substrate substrates semiconductor semiconductors))	USPAT; US-PGPUB;	2004/08/04 08:34
		with (condition conditioner conditioning conditions conditioners)	EPO; JPO; DERWENT; IBM TDB	
36	32	((dummy with (wafer wafers substrate substrates semiconductor semiconductors)) with (condition conditioner conditioning conditions conditioners)) and 451/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/08/04 08:35
37	96	((dummy with (wafer wafers substrate substrates semiconductor semiconductors)) and (condition conditioner conditioning conditions conditioners)) and 451/\$.ccls.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 08:35
38	64	(((dummy with (wafer wafers substrate substrates semiconductor semiconductors)) and (condition conditioner conditioning conditions conditioners)) and 451/\$.ccls.) not (((dummy with (wafer wafers substrate substrates semiconductor semiconductors)) with (condition conditioner conditioning conditions conditioners)) and 451/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:38
39	1140	451/6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 09:29
41	235	((friction torque) same (distance gap) same (sensor sensors sensing senses sense)) and(strain adj gauge)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 09:31
42	32	((friction torque) same (distance gap) same (sensor sensors sensing senses sense))same(strain adj gauge)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 09:32
43	3	<pre>(((friction torque) same (distance gap) same (sensor sensors sensing senses sense))same(strain adj gauge)) and (wafer wafers substrate substrates semiconductor semiconductors)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 09:38
44	2664	dummy adj (wafer wafers substrate substrates semiconductor semiconductors)	USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 09:39
45	285	(condition conditioner conditioning conditions conditioners) with (dummy adj (wafer wafers substrate substrates semiconductor semiconductors))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 09:39
46	0	((condition conditioner conditioning conditions conditioners) with (dummy adj (wafer wafers substrate substrates semiconductor semiconductors))) with arm	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 09:39
47	1	((condition conditioner conditioning conditions conditioners) with (dummy adj (wafer wafers substrate substrates semiconductor semiconductors))) same arm	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 09:39
49	0	(((condition conditioner conditioning conditions conditioners) with (dummy adj (wafer wafers substrate substrates semiconductor semiconductors))) and 451/\$.ccls.) and wheels	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 09:40

			<u> </u>	-
48	26	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	USPAT;	2004/08/04 09:41
		conditions conditioners) with (dummy adj	US-PGPUB;	1
1		(wafer wafers substrate substrates	EPO; JPO;	
		semiconductor semiconductors))) and	DERWENT;	
		451/\$.ccls.	IBM TDB	
50	155624	"L-shaped"	USPAT;	2004/08/04 09:42
. 30	133024	L-Shaped	l ·	2004/00/04 03.42
			US-PGPUB;	
			EPO; JPO;	
	Į.		DERWENT;	
	ĺ		IBM_TDB	
51	803	"L-shaped" and 451/\$.ccls.	USPAT;	2004/08/04 09:42
		-	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
52	147	("L-shaped" and 451/\$.ccls.) and (wafer	USPAT;	2004/08/04 09:45
52	14/			2004/08/04 09:43
		wafers substrate substrates semiconductor	US-PGPUB;	
		semiconductors)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
53	1109	451/56	USPAT;	2004/08/04 10:11
	ŀ		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
64	0			2004/08/04 10:11
54	0	"scott e. moore.".in.	USPAT;	2004/08/04 10:11
			US-PGPUB;	
1			EPO; JPO;	
ł			DERWENT;	
			IBM TDB	
55	10	(scott adj3 moore).in.	USPAT;	2004/08/04 10:11
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
5.0	267			0004/00/04 10:10
56	267	scott with moore	USPAT;	2004/08/04 10:12
	1		US-PGPUB;	
			EPO; JPO;	
	ļ		DERWENT;	
			IBM_TDB	-
57	248	scott near3 moore	USPAT;	2004/08/04 10:12
			US-PGPUB;	
			EPO; JPO;	İ
			DERWENT;	
			IBM TDB	1
E0	1010	machuha un	USPAT;	2004/08/04 10:12
58	1910	rachuba.xp.		2004/08/04 10:12
	1		US-PGPUB;	
			EPO; JPO;	j i
			DERWENT;	
	1		IBM_TDB	
59	6	(scott near3 moore) and rachuba.xp.	USPAT;	2004/08/04 10:12
	ļ	<u> </u>	US-PGPUB;	l i
	ļ		EPO; JPO;	
	1		DERWENT;	
1			IBM TDB	
60	1		USPAT	2004/08/04 10:14
l l	1			
61	1 1		USPAT	2004/08/04 10:15
62	1 1		USPAT	2004/08/04 10:15
63	1		USPAT	2004/08/04 10:15
64	1		USPAT	2004/08/04 10:15
65	1		USPAT	2004/08/04 10:15
66	1		USPAT	2004/08/04 10:16
67	1		USPAT	2004/08/04 10:16
68	1		USPAT	2004/08/04 10:16
69	1		USPAT	2004/08/04 10:16
70	1		USPAT	2004/08/04 10:16
70	1		USPAT	2004/08/04 10:10
	_			
72	1		USPAT	2004/08/04 10:17
73	1		USPAT	2004/08/04 10:17
74	1		USPAT	2004/08/04 10:17
75	1		USPAT	2004/08/04 10:17